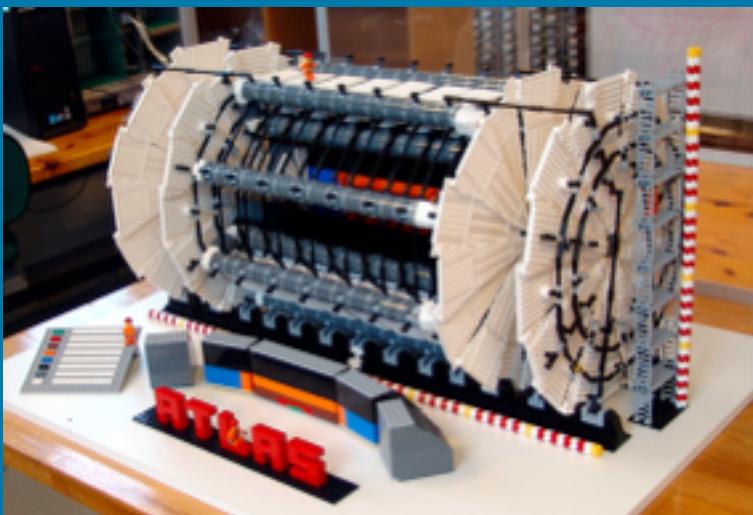




DETECTORS FOR HIGH ENERGY PHYSICS



Ingrid-Maria Gregor, DESY

DESY Summer Student Program 2017
Hamburg
July 26th/27th

OVERVIEW

I. Detectors for Particle Physics

II. Interaction with Matter

III. Calorimeters

IV. Tracking Detectors

- Gas detectors
- Semiconductor trackers

V. Examples from the real life

{

Wednesday

{

Thursday

IV. TRACKING DETECTORS

TRACKING

- “tracking” in google image search:



TRACKING DETECTOR

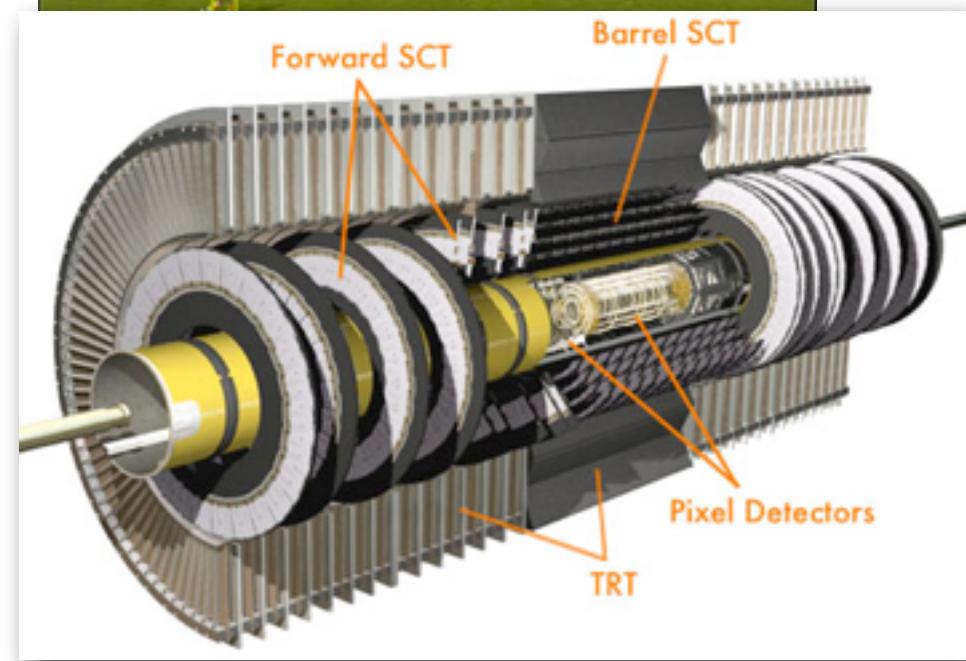
- “tracking detector” in google image search



GPS Tracking Detector

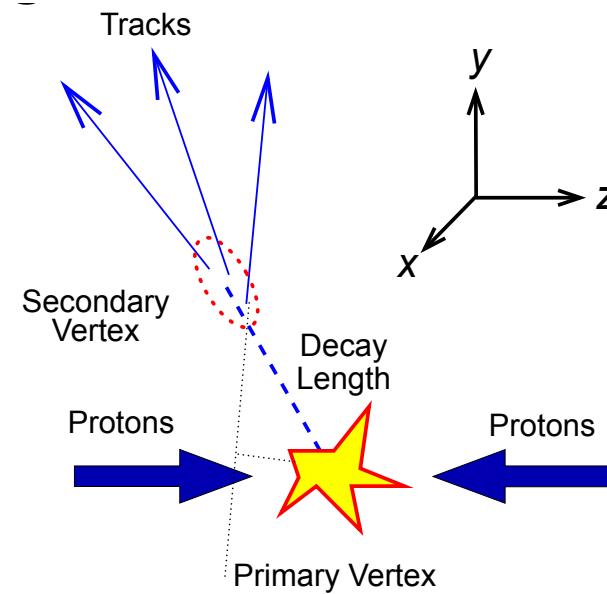
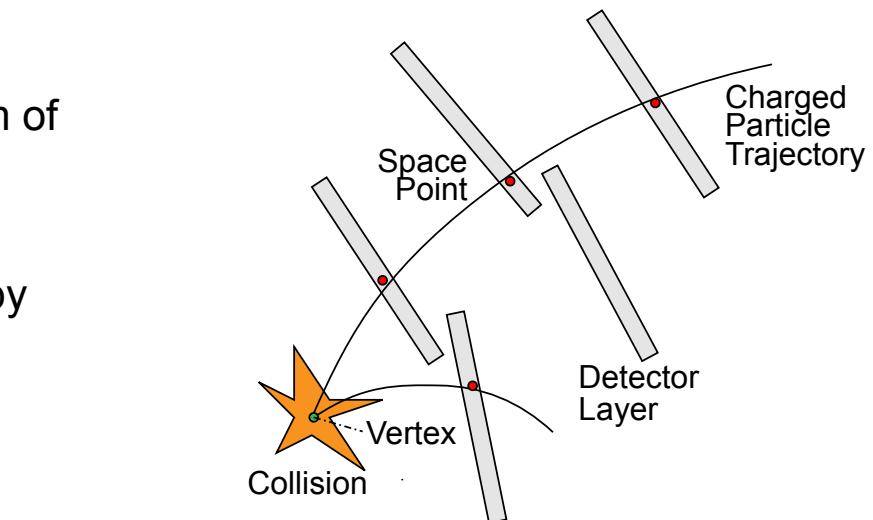


But the 1st image on list is:



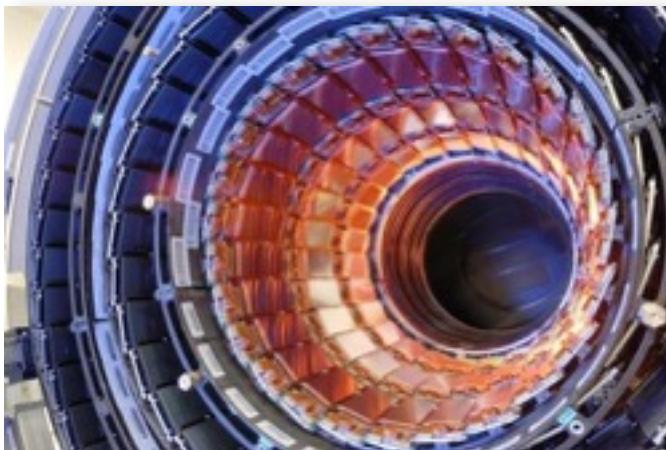
TRACKING DETECTORS

- Precise measurement of track and momentum of charged particles due to magnetic field.
- The trajectory should be disturbed minimally by this process (reduced material)
- Charged particles ionize matter along their path.
 - Tracking is based upon detecting ionisation trails.
 - An “image” of the charged particles in the event

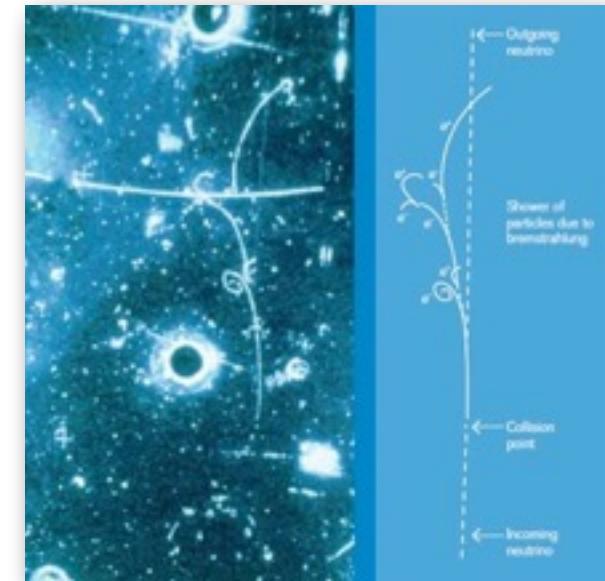


TRACKING DETECTORS - TECHNOLOGIES

- “Classic”: Emulsions, cloud, and bubble chambers
 - Continuous media
 - Typically very detailed information but slow to respond and awkward to read out
- “Modern”: Electronic detectors, wire chambers, scintillators, solid state detectors
 - Segmented
 - Fast, can be read out digitally, information content is now approaching the “classic” technology
 - Mostly used solid state detector -> Silicon (pixels and strips)



CMS Inner barrel Si Tracker:
Single-Sided Si-Strip

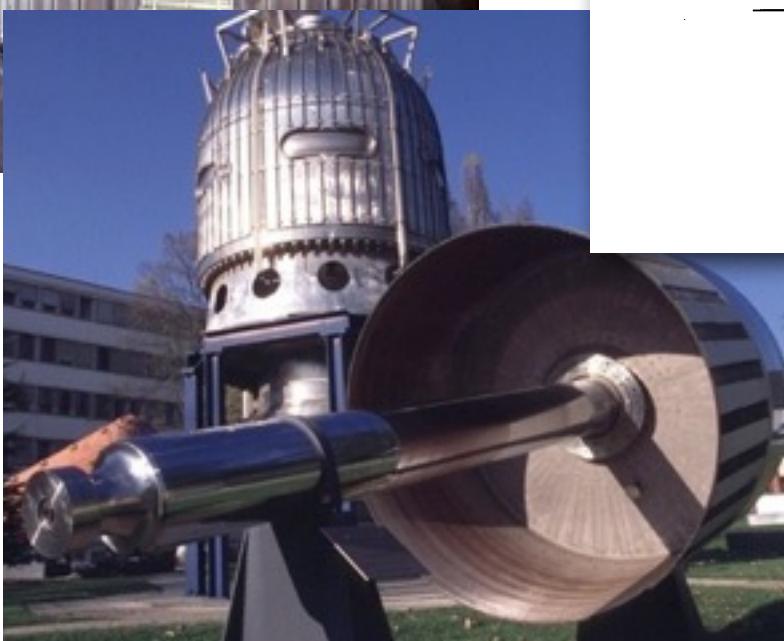
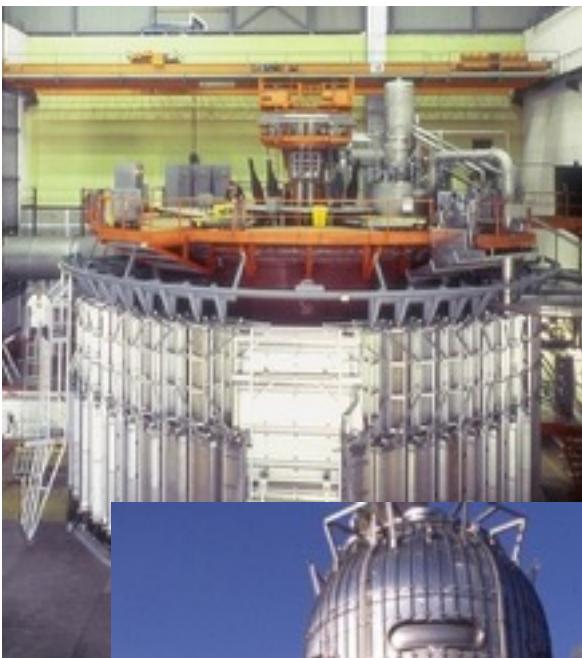


Discovery of neutral currents
Gargamelle, 1972



Pictures: CERN

VERY “CLASSIC”: BUBBLE CHAMBER



- The biggest: Big European Bubble Chamber
- 3.7 m diameter
- Until 1984 used at CERN for the investigation of neutron hadron interactions

Early report on bubble chamber analysis:



Second United Nations
International Conference
on the Peaceful Uses of
Atomic Energy

A/CONF.15/P/730
U.S.A.
June 1958

ORIGINAL: ENGLISH

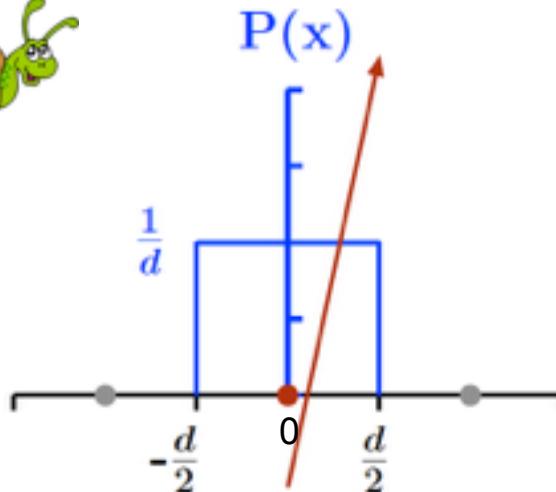
ON THE ANALYSIS OF BUBBLE CHAMBER TRACKS

Hugh Bradner and Frank Solmitz

“... the large number of possible reactions, the variability of appearance of interaction, and the importance of being alert to possible new phenomena make it very important for a **trained physicist** to look at the bubble chamber pictures....”

TRACKER: IMPORTANT PARAMETER

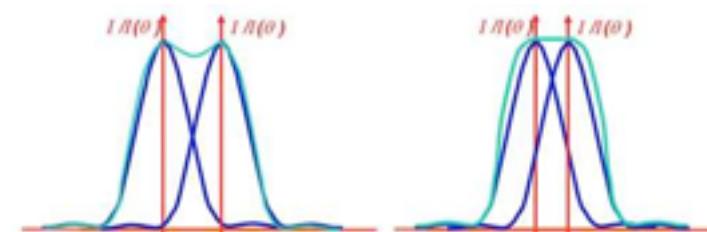
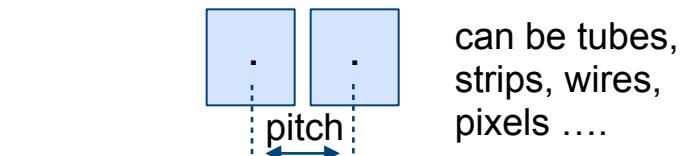
- An important figure of merit is the **spatial resolution** of a tracking detector
- Depending on detector geometry and charge collection
 - Pitch (distance between channels)
 - Charge sharing between channels
- Simple case: all charge is collected by one strip
- Traversing particle creates signal in hit strip (binary)
- Flat distribution along strip pitch; no area is pronounced
- Probability distribution for particle passage:



$$P(x) = \frac{1}{d} \quad \Rightarrow \quad \int_{-d/2}^{d/2} P(x) dx = 1$$

The reconstructed point is always the middle of the strip:

$$\langle x \rangle = \int_{-d/2}^{d/2} x P(x) dx = 0$$



TRACKER: IMPORTANT PARAMETER

- Calculating the resolution orthogonal to the strip:

$$\sigma_x^2 = \langle (x - \langle x \rangle)^2 \rangle = \int_{-d/2}^{d/2} x^2 P(x) dx = \frac{d^2}{12}$$

- Resulting in a general term (valid for tracking detectors with a pitch d):

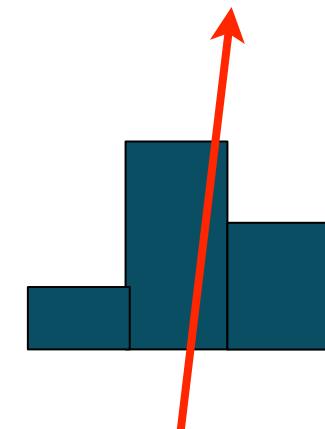
$$\sigma = \frac{d}{\sqrt{12}}$$



very important !

- For a silicon strip detector with a strip pitch of 80 µm this results in a minimal resolution of ~23µm
- In case of charge sharing between the strip (signal size decreasing with distance to hit position) and information about signal size
 - resolution improved by additional information of adjacent channels

$$\sigma \propto \frac{d}{(S/N)}$$



TRACKING: DETERMINATION OF THE MOMENTUM IN MAGNETIC FIELD

- A tracking detector is typically placed within a B-field to enable momentum measurements
- Charged particles are deflected in a magnetic field:
 - takes only effect on the component perpendicular to the field

Radius of the circular path is proportional to the transversal momentum

$$F = qvB$$

$$ma = qvB$$

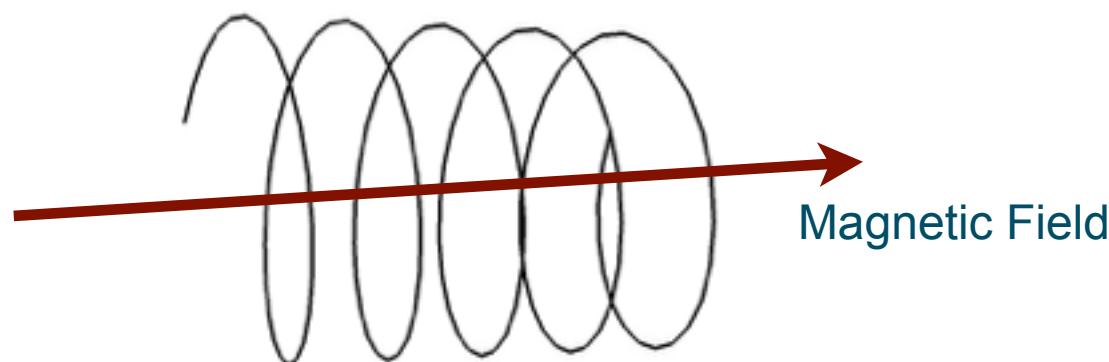
$$m\left(\frac{v^2}{r}\right) = qvB$$

$$p = 0.3Br$$

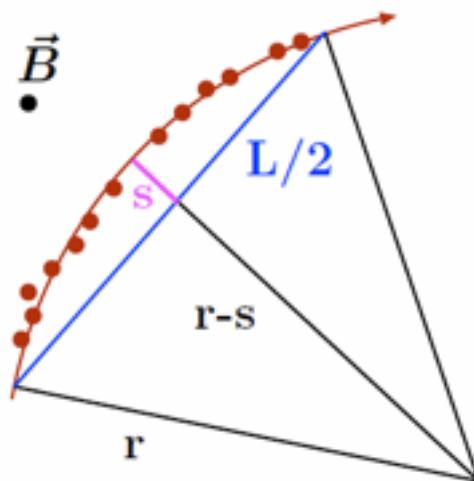
- parallel to the field is no deflection:

when converting in HEP units and assuming that all particles have the |electron charge|

⇒ particle is moving on a helix, the radius is determined by the field and p_T



DETERMINATION OF THE MOMENTUM IN MAGNETIC FIELD II



- In real applications usually only slightly bent track segments are measured
- Figure of merit: sagitta

Segment of a circle: $s = r - \sqrt{r^2 - \frac{L^2}{4}}$

$$\Rightarrow r = \frac{s}{2} + \frac{L^2}{8s} \approx \frac{L^2}{8s} \quad (s \ll L)$$

With the radius-momentum-B-field relation: $r = \frac{p_T}{0.3B} \Rightarrow s = \frac{0.3BL^2}{8p_T}$

Momentum resolution due to position measurement:

Gluckstern

$$\frac{\sigma_{p_T}}{p_T} = \frac{\sigma_s}{s} = \sqrt{\frac{720}{n+4} \frac{\sigma_y p_T}{0.3BL^2}}$$

NIM, 24, P381, 1963

- The larger the magnetic field **B**, the length **L** and the number of measurement points **n**, and the better the spatial resolution, the better is the momentum resolution

IMPULS RESOLUTION: SPATIAL RESOLUTION AND MULTIPLE SCATTERING

- More components are influencing the momentum resolution $\sigma(p_T)/p_T$ of a tracking system:

- Inaccuracy of the tracking detector: $\sigma(p_T) \propto p_T$

- Influence of the particle due to MS: $\sigma(x)_{MS} \propto \frac{1}{p}$

- The angular resolution of the detector

Multiple scattering angle: $\theta \propto \frac{1}{p}$

$$\left(\frac{\sigma_{p_T}}{p_T}\right)^2 = \left(\sqrt{\frac{720}{n+4} \frac{\sigma_y p_T}{0.3 B L^2}}\right)^2 + \left(\frac{52.3 \times 10^{-3}}{\beta B \sqrt{L L_y \sin \theta}}\right)^2 + (\cot \theta \sigma_\theta)^2$$

Position resolution

Multiple scattering

Angular resolution

- p_T resolution improves as $1/B$ and depends on p as $1/L^2$ or $1/L^{-1/2}$
- For low momentum ($\beta \rightarrow 0$), MS will dominate the momentum resolution.
- Improving the spatial resolution (σ_y) only improves momentum resolution if the first term is dominate.

TRACKER: IMPORTANT PARAMETER

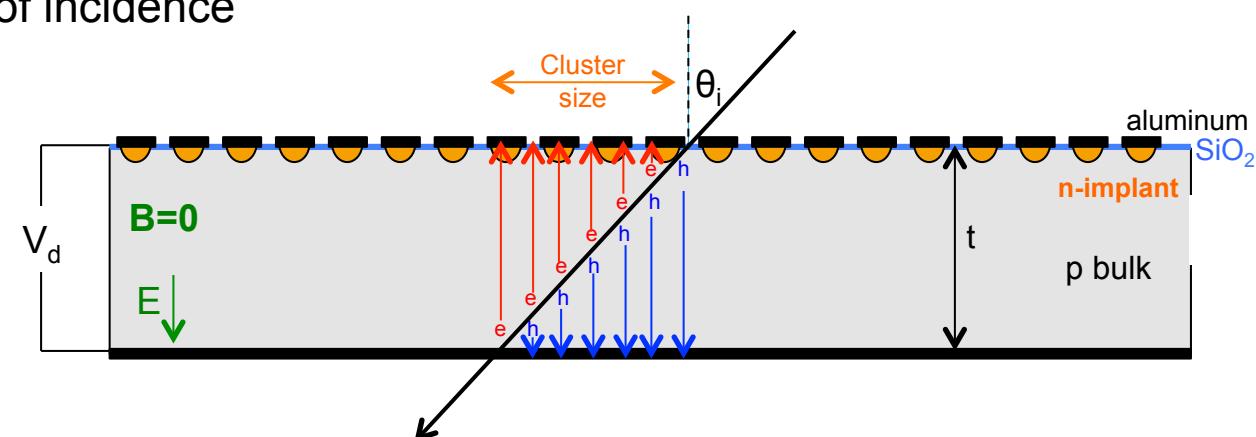
- Detector efficiency ϵ : probability to detect a transversing particle
 - should be as close to 100% as possible
 - i.e. 12 layer silicon detector with 98% efficiency per layer -> overall tracking efficiency is only 78%
 - needs to be measured in test beam

$$\epsilon_{\text{track}} = (\epsilon_{\text{layer}})^n$$

n = number of layers in tracking system

- Cluster size : number of hit pixels/strips belonging to one track
 - usually given in unit of strips or pixels
 - depending on angle of incidence

Optimally measured in test beam



TRACKER: IMPORTANT PARAMETER

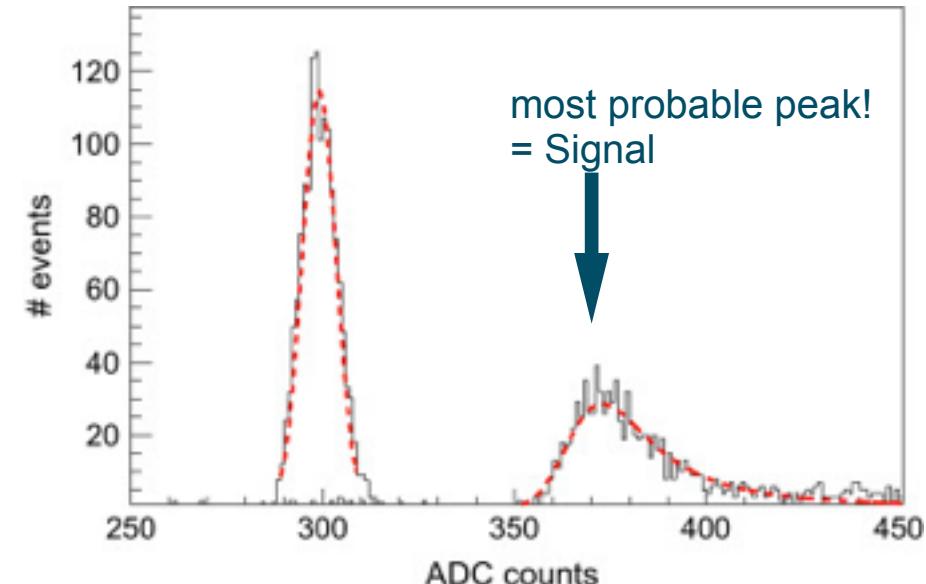
- **Signal/noise ratio:** signal size for a certain input signal over the intrinsic noise of the detector
 - parameter for analog signals
 - good understanding of **electrical noise charge** needed
 - leakage current (ENC_I)
 - detector capacity (ENC_C)
 - det. parallel resistor (ENC_{R_p})
 - det. series resistor (ENC_{R_s})
- signal induced by source or laser (or test beam particles)
- optimal S/N for a MiP is larger than 20

$$\text{ENC} = \sqrt{\text{ENC}_C^2 + \text{ENC}_I^2 + \text{ENC}_{R_p}^2 + \text{ENC}_{R_s}^2}$$

example for silicon detector

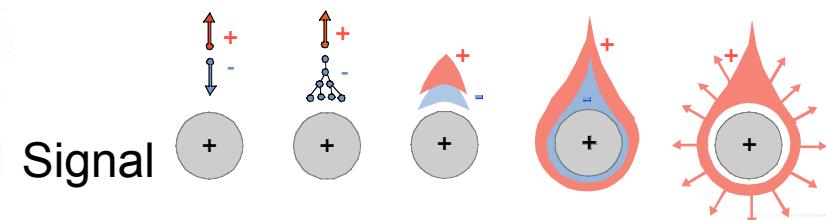
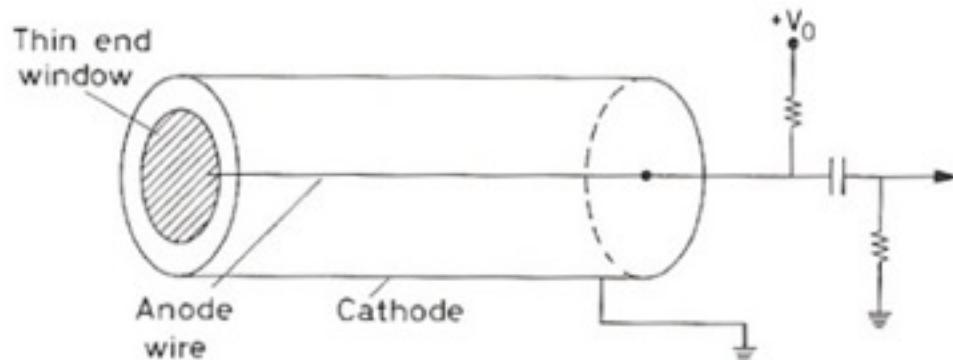
With analog readout:

Gaussian distributed “non-signal”
= sigma -> noise

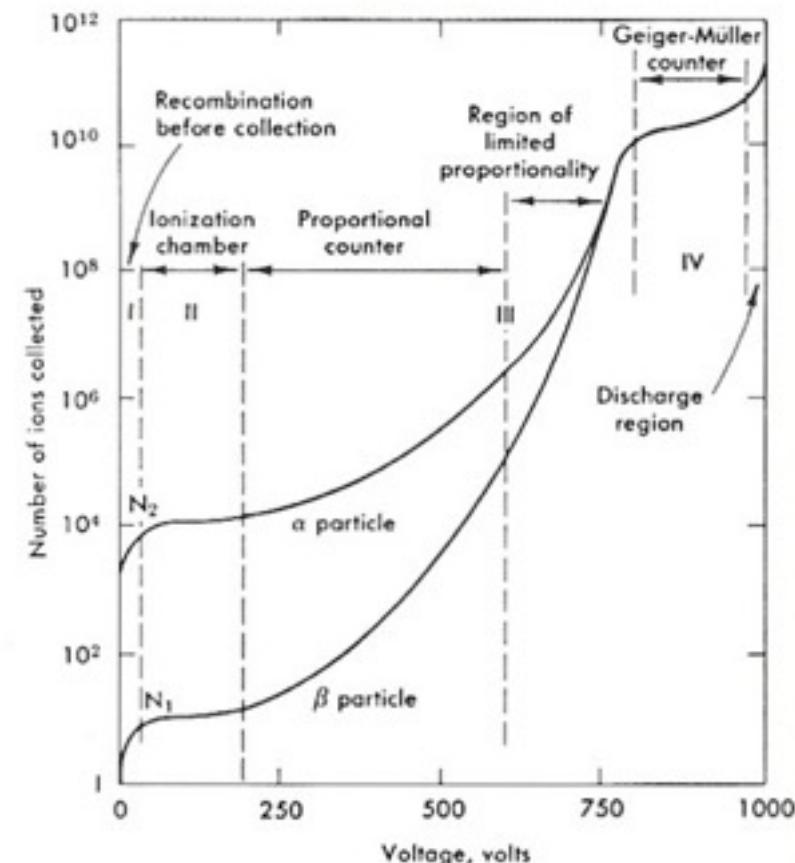


IV.A GAS-DETECTORS

ANOTHER CLASSIC: IONISATION CHAMBER

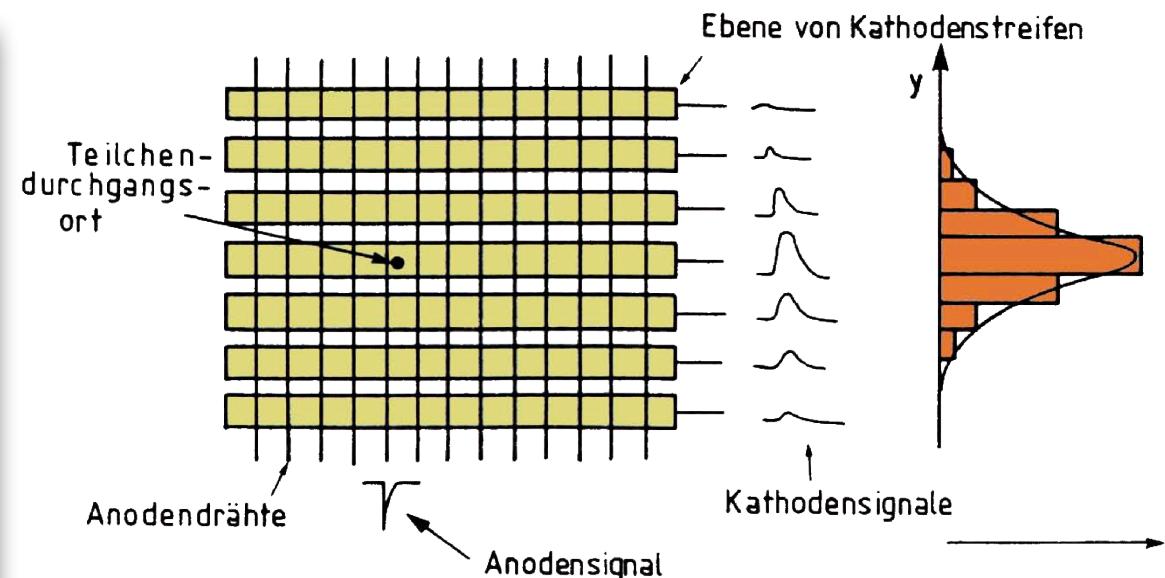
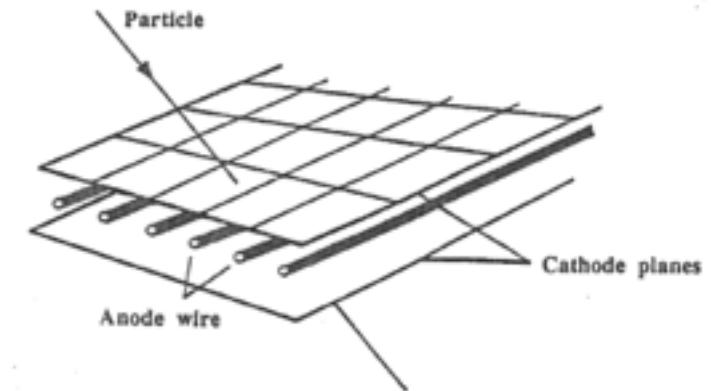


- Passage of particles creates within the gas volume electron-ion pair (ionisation)
- Electrons are accelerated in a strong electric field -> amplification
- The signal is proportional to the original deposited charge or is saturated (depending on the voltage)



CONTINUATION OF IONISATION CHAMBERS

- Extreme successful approach to improve the spatial resolution of gas detectors
- Multi wire proportional chamber (MWPC)
- Gas-filled box with a large number of parallel detector wires, each connected to individual amplifiers
- G. Charpak 1968
(Nobel-prize 1992)



ADDING THE TIME: DRIFT CHAMBER

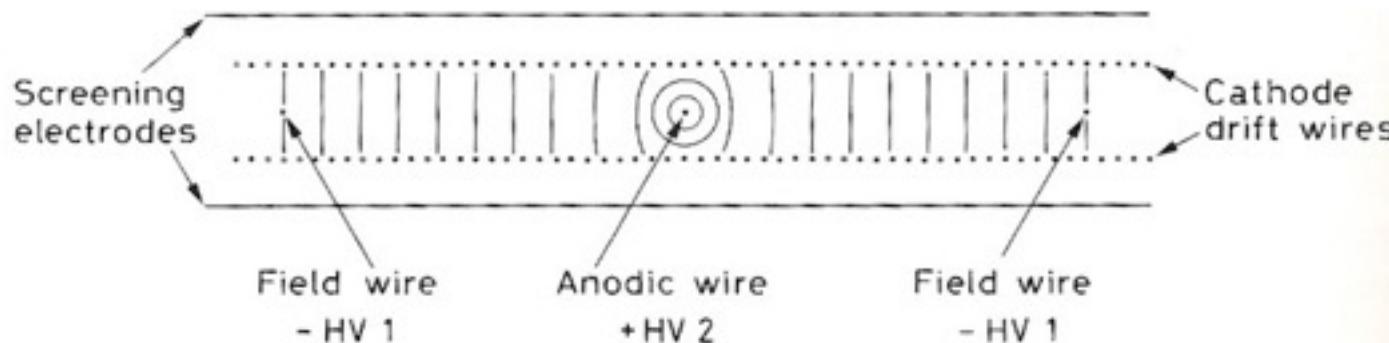
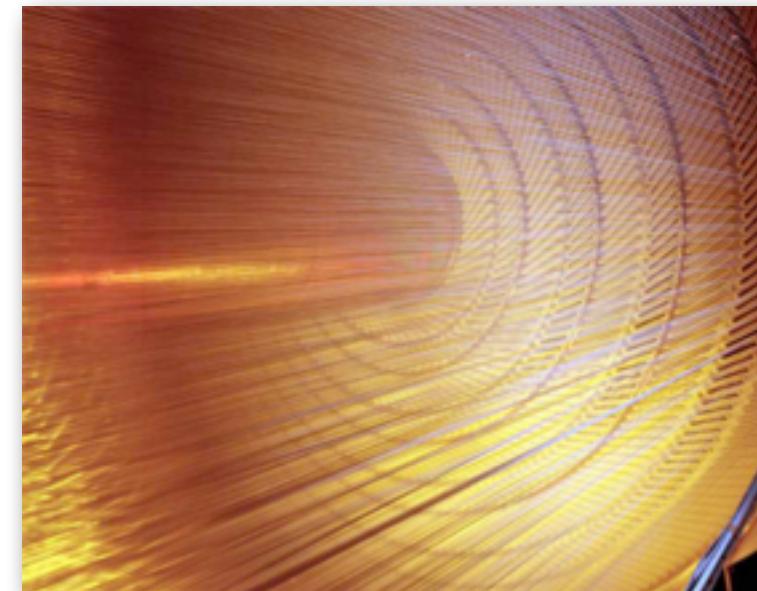


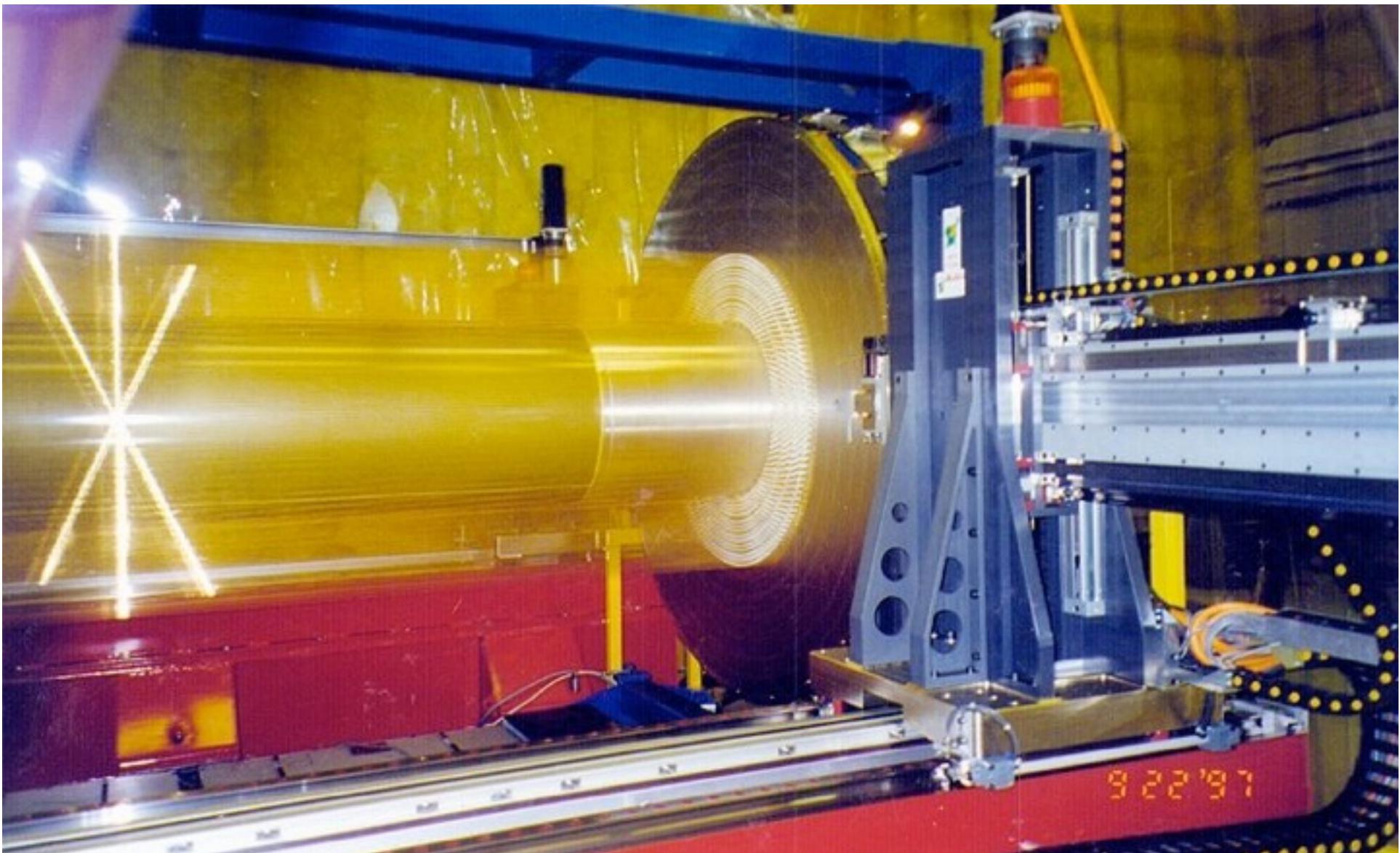
Fig. 6.16. Drift chamber design using interanode field wires (from *Breskin et al. [6.22]*)

- Electric field is designed in a way that electrons drift with a constant velocity and only amplify very close to the wire
- If time of arrival of a particle is known (trigger), one can derive from the signal arrival time at the anode the position of the track
- Condition: the HV field distribution and therefore the drift velocity within the gas is well known

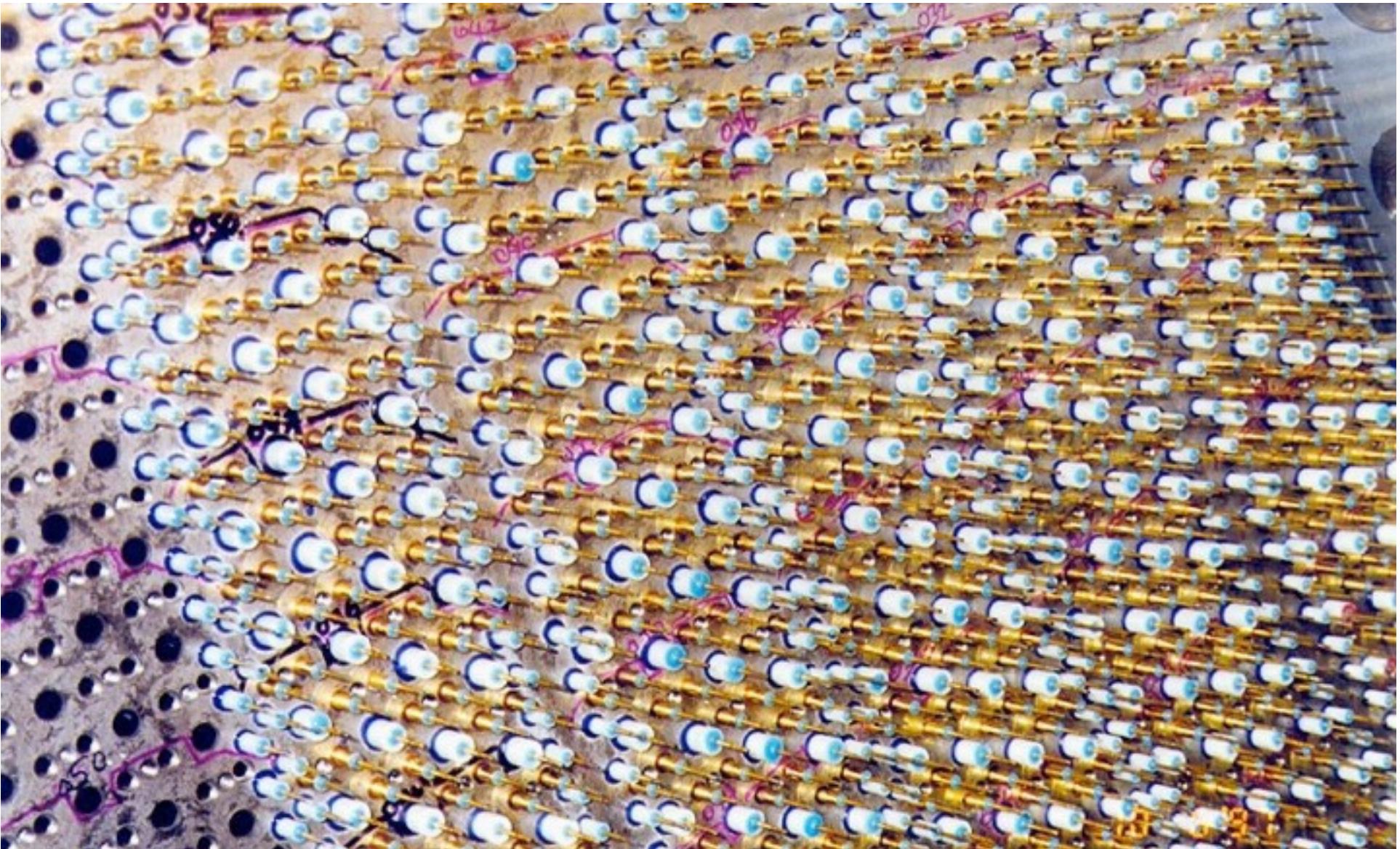


Wire chamber CDF (@Tevatron)

WIRE STRINGING IN PROGRESS



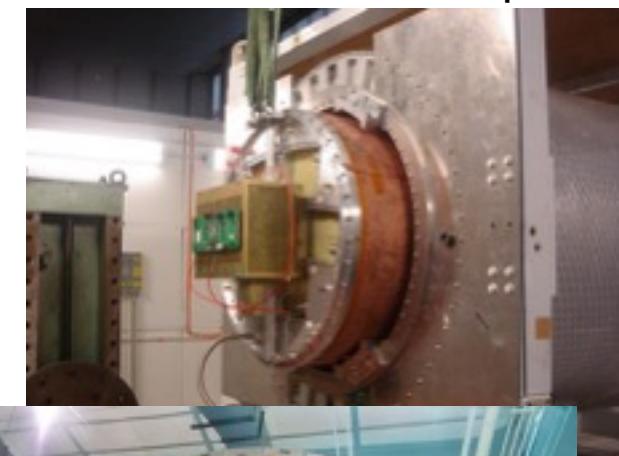
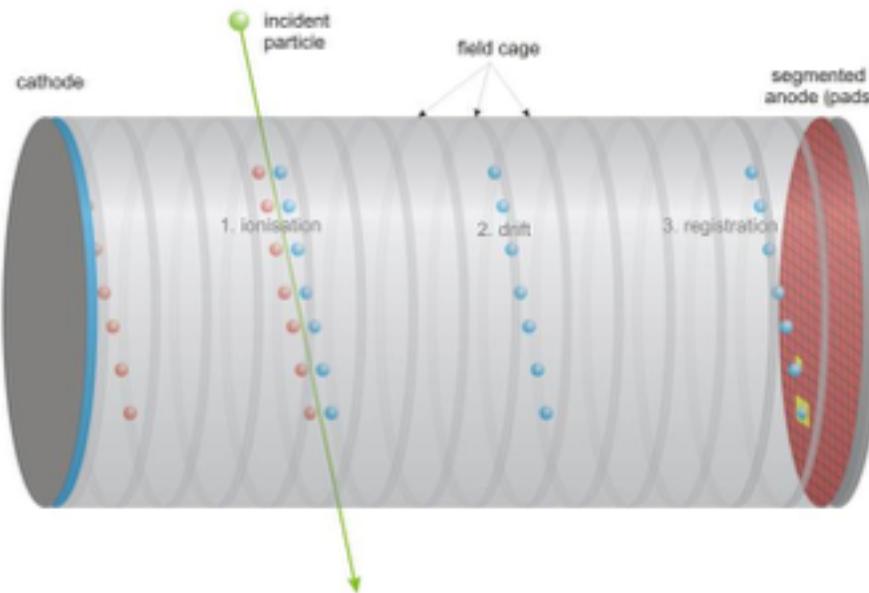
END PLATE CLOSE UP



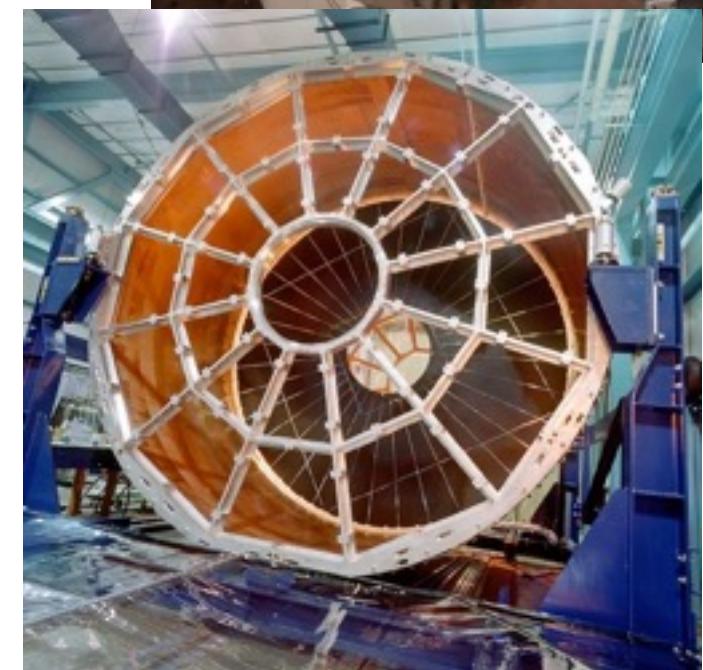
TPC- TIME PROJECTION CHAMBER: 3D

- Combination of the the 2D track information and the time results in a real 3D point

Pic: O. Schäfer



Pic: DESY



Pic: ALICE Collaboration

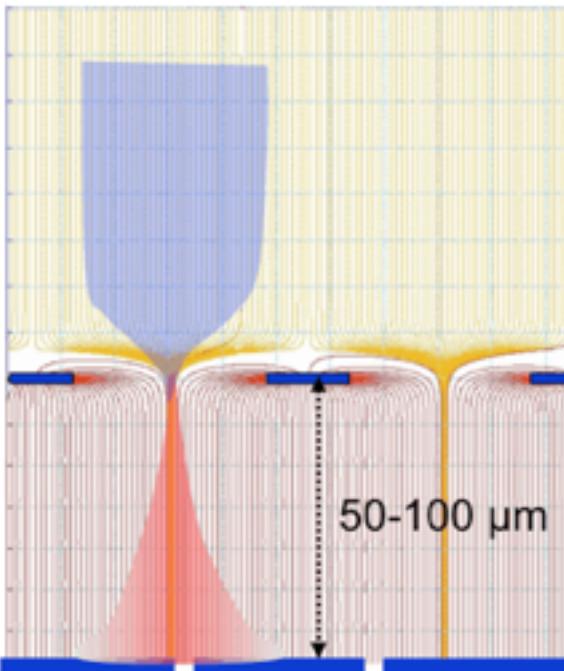
- Readout of the anode usually with multi wire projection chambers
- Nowadays new developments under way.

NEW DEVELOPMENTS

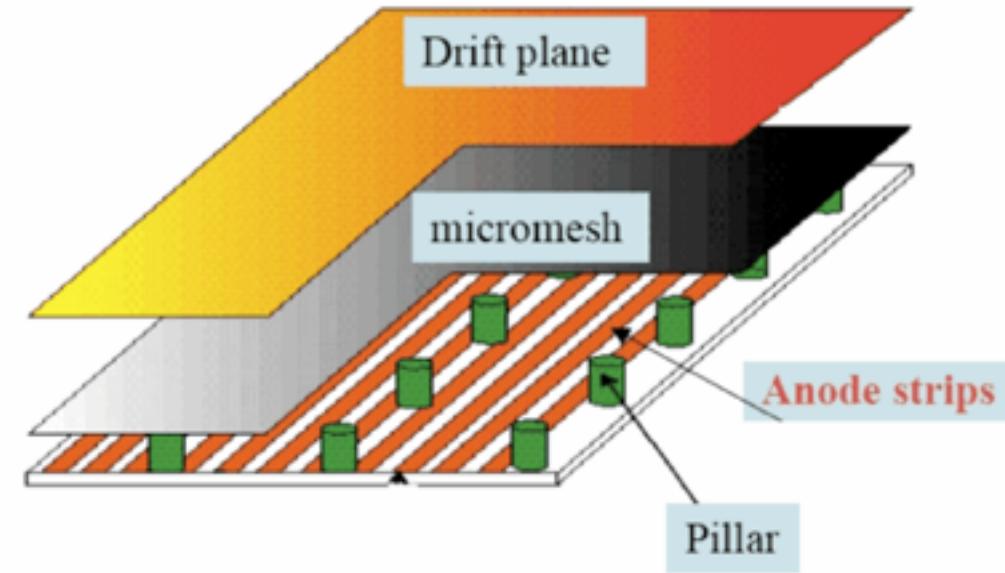
- Largely improved spacial resolution and higher particle rates:

Micro-Pattern Gas Detectors

- a number of developments were started, some with a lot of problems
- two technologies are currently the most successful: GEMs and MicroMegas
- MicroMegas: Avalanche amplification in a small gap

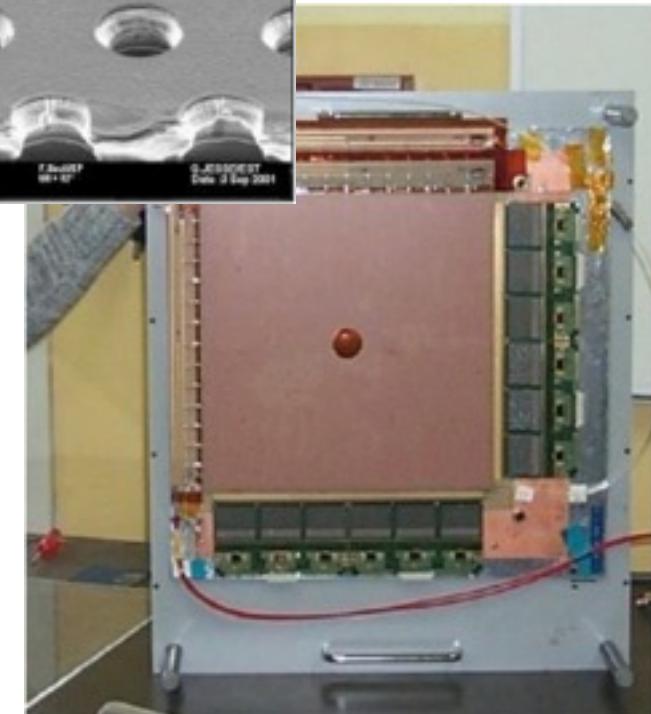
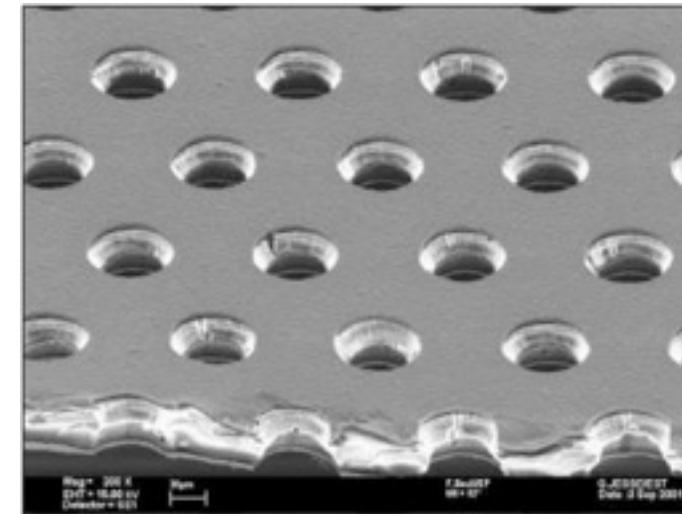
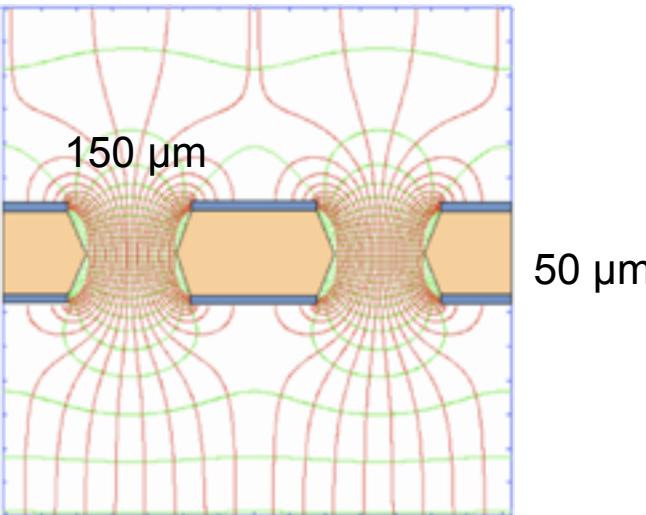


Y. Giomataris et al, NIM A376, 29(1996)



NEW DEVELOPMENTS

- GEM: Gas Electron Multiplier: Gas amplification in small holes in a special foil

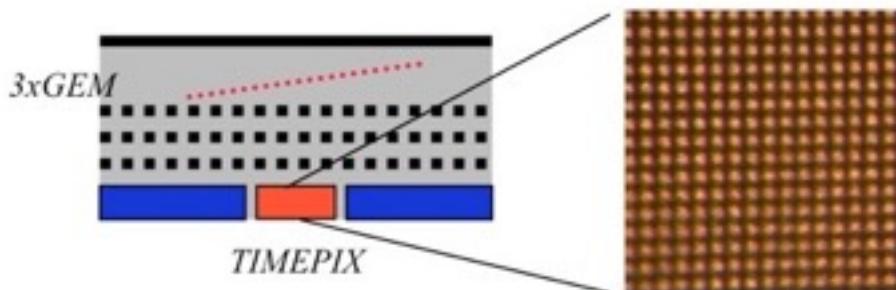


Charge collection on two separate levels: 2D structure
possible: separation of amplification and read out

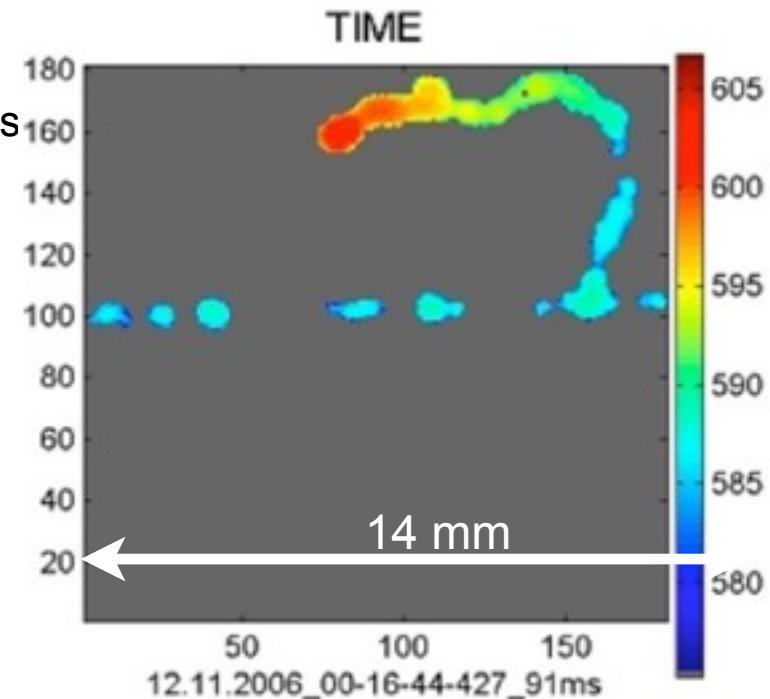
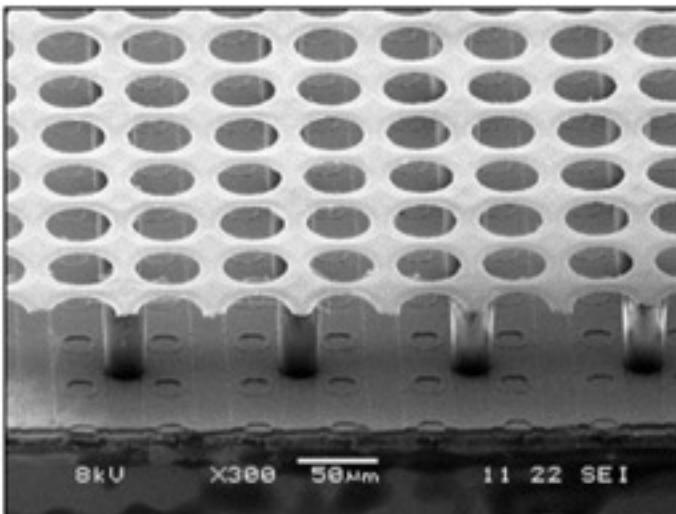
Both technologies, MicroMegas and GEMs are used in experiments. Typical spacial resolution: ~70 um

MPGDs AS NEXT GENERATION DETECTOR

- Combination of gas detectors and Silicon
- Integration of MPGDs with pixel read out chips



- Amplification and read out made of silicon

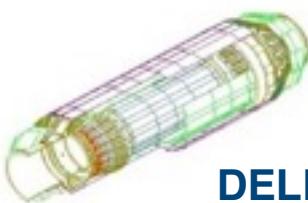


Advantages of gas detectors:

- Low radiation length
- Gas can be replaced regularly: Reduction of radiation damages!

V.B SEMICONDUCTOR-DETECTORS

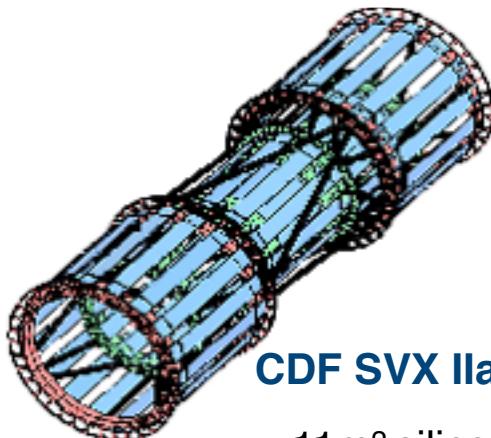
LARGE SILICON SYSTEMS



DELPHI (1996)

~ 1.8m² silicon area

~ 175 000 readout channels

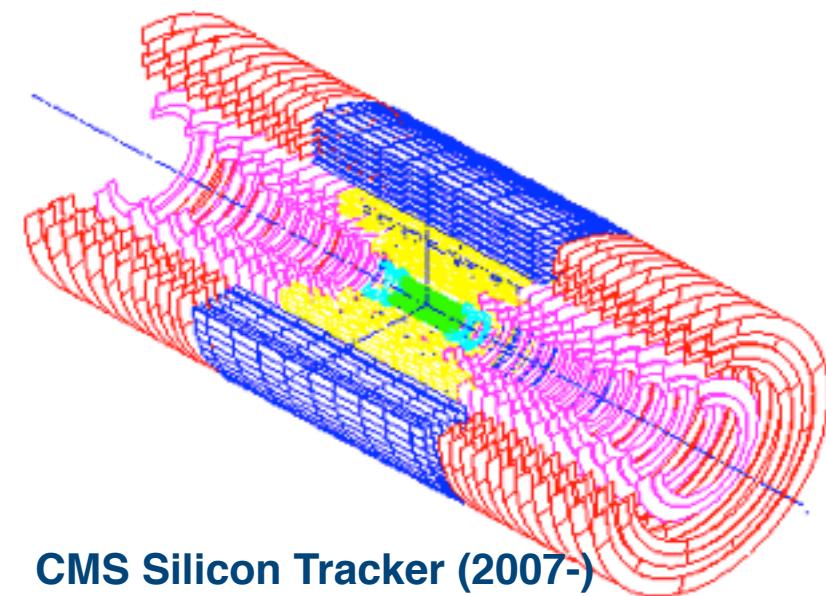


CDF SVX IIa (2001-2012)

~ 11m² silicon area

~ 750 000 readout channels

Since ~ 30 years: Semiconductor detectors for precise position measurements.



CMS Silicon Tracker (2007-)

~12,000 modules

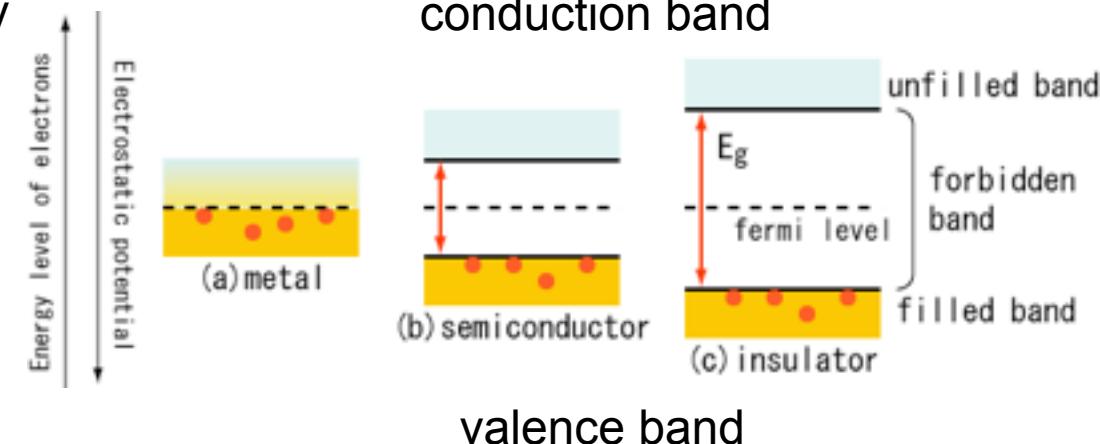
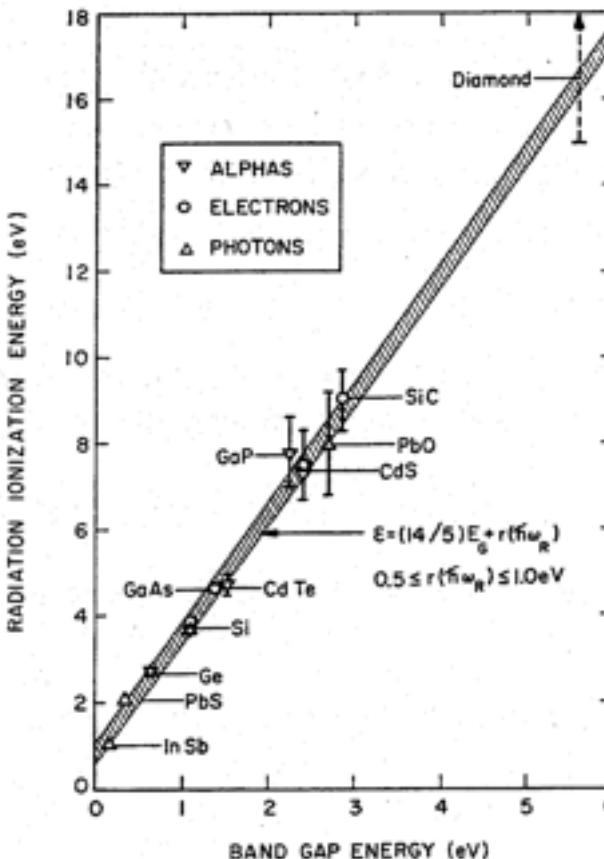
~ 223 m² silicon area

~25,000 silicon wafers

~ 10M readout channels

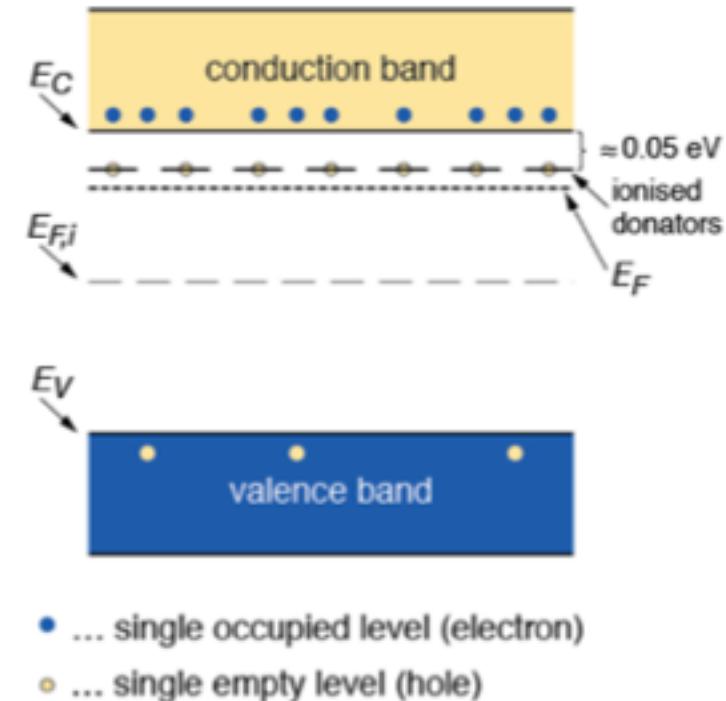
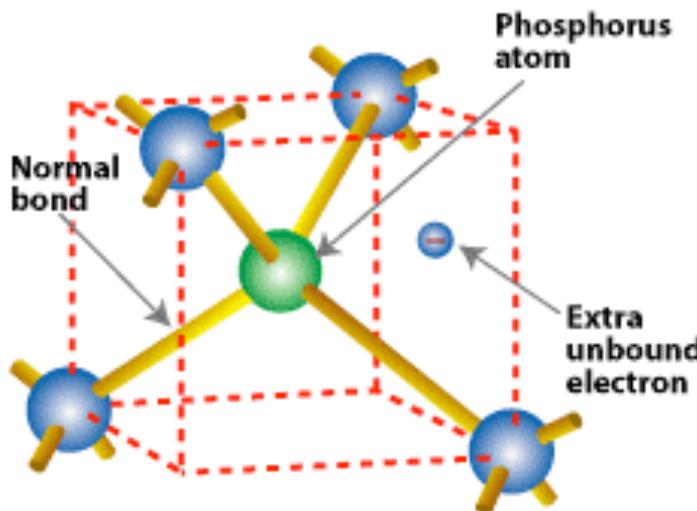
SEMICONDUCTOR BASICS I

- In free atoms the electron energy levels are discrete.
- In a solid, energy levels split and form a nearly-continuous band.



- Large gap: the solid is an insulator.
- No gap: it is a conductor.
- Small band gap: semiconductor
- For silicon, the band gap is 1.1 eV, but it takes 3.6 eV to ionize an atom \rightarrow rest of the energy goes to phonon excitations (heat).

DOPING SILICON

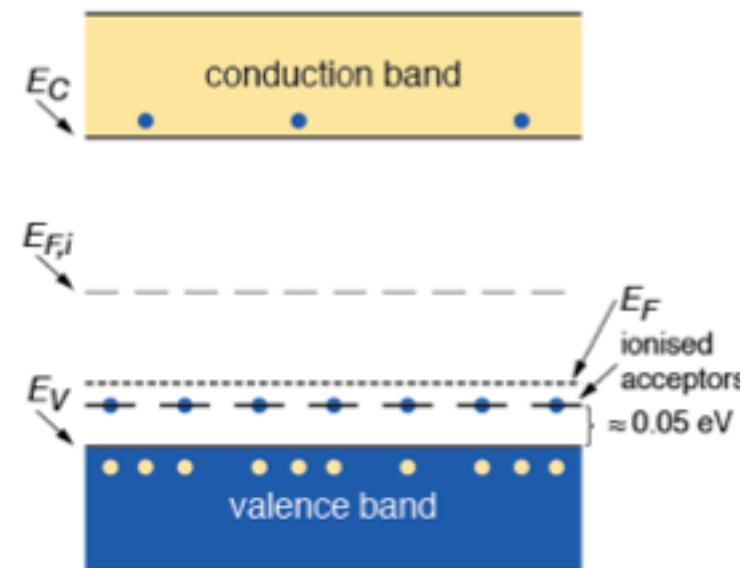
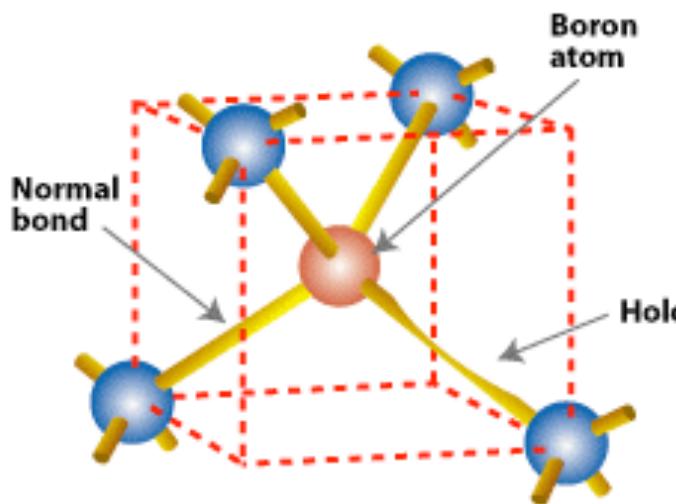


n-type:

- ◎ In an n-type semiconductor, negative charge carriers (electrons) are obtained by adding impurities of donor ions (eg. Phosphorus (type V))
- ◎ Donors introduce energy levels close to conduction band thus almost fully ionized

Electrons are the majority carriers.

DOPING SILICON



- ... single occupied level (electron)
- ... single empty level (hole)

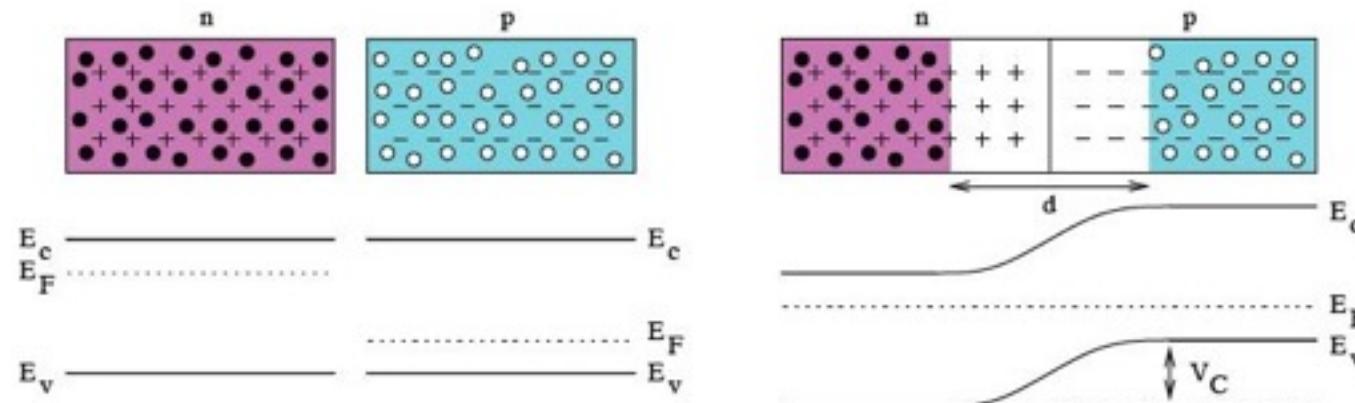
p-type:

- ◎ In a p-type semiconductor, positive charge carriers (holes) are obtained by adding impurities of acceptor ions (eg. Boron (type III)).
- ◎ Acceptors introduce energy levels close to valence band thus ‘absorb’ electrons from VB, creating holes

Holes are the majority carriers.

PN-JUNCTION

- p- and n-doped semiconductor combined
- Gradient of electron and hole densities results in a diffuse migration of majority carriers across the junction.
- Migration leaves a region of net charge of opposite sign on each side, called the depletion region (depleted of charge carriers).



- Artificially increasing this depleted region by applying a **reversed bias voltage** allows charge collection from a larger volume

$$d = \sqrt{\frac{2\epsilon\epsilon_0 V}{e} \left(\frac{1}{n_D} + \frac{1}{n_A} \right)} \quad \text{with} \quad n_A \gg n_D \quad d = \sqrt{\frac{2\epsilon\epsilon_0 V}{en_D}}$$

PRINCIPLE OF SEMICONDUCTOR

1. Creation of electric field: voltage to

$$V_{\text{dep}} = d^2 N_{\text{eff}} \frac{q}{2\epsilon\epsilon_0}$$

N_{eff} : doping concentration

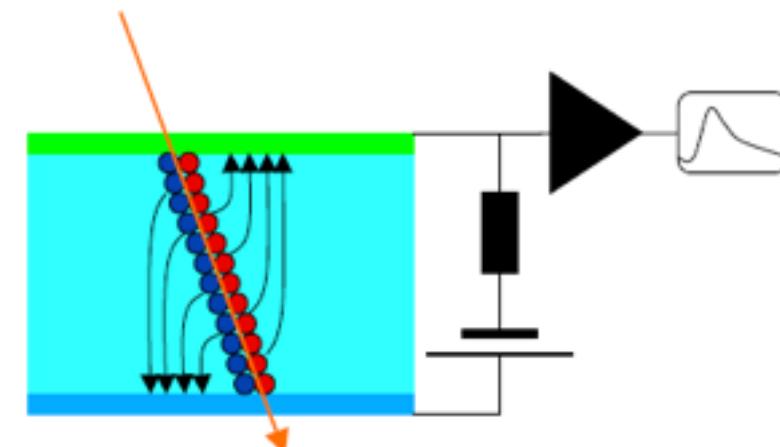
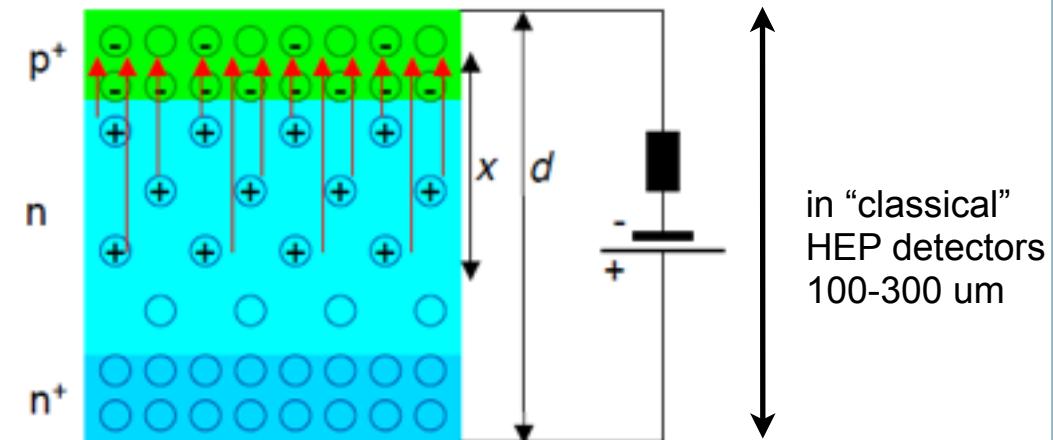
2. Keep leakage current low

$$I \propto \frac{1}{\tau_g} \cdot T^2 \cdot \exp^{-\frac{E_g}{2kT}} \times \text{volume}$$

τ_g : charge carrier life time

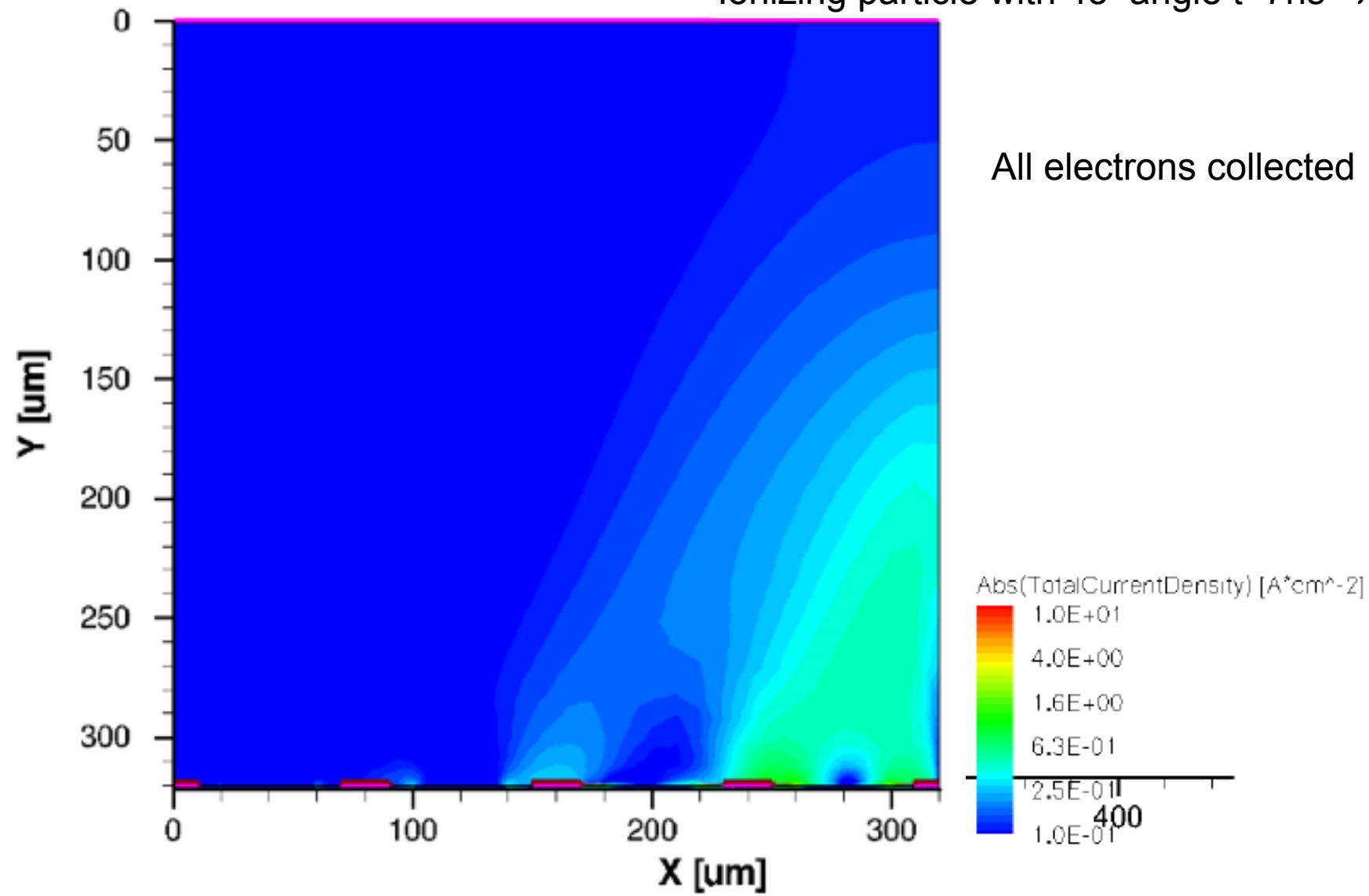
3. Ionising particles create free charge carrier

4. Charge carrier drift to electrodes and induce signal



CURRENT DENSITY

Ionizing particle with 45° angle t=7ns ;

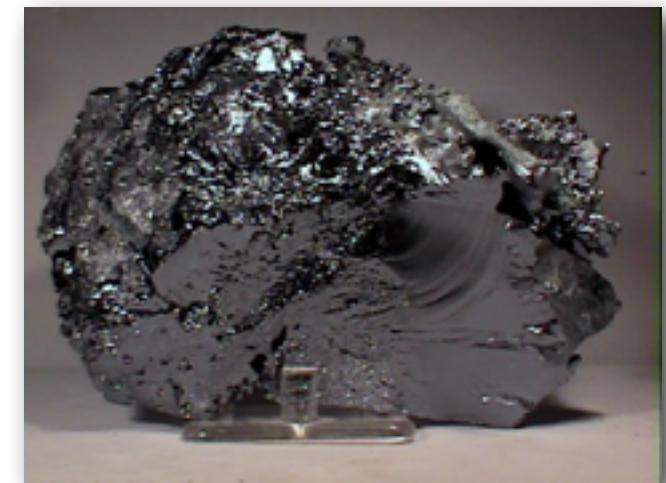


MATERIAL PROPERTIES

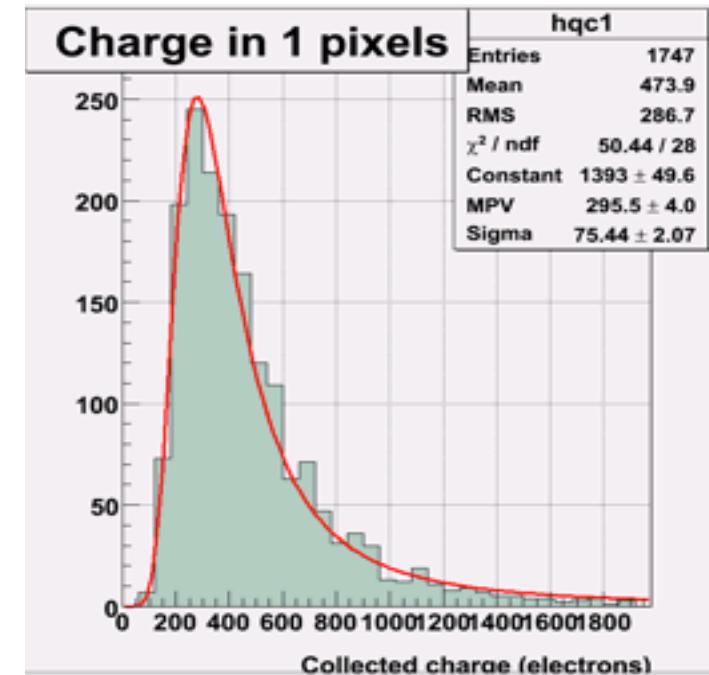
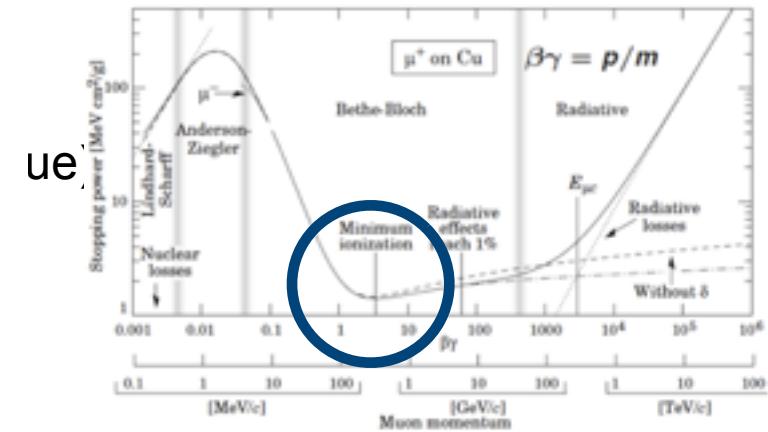
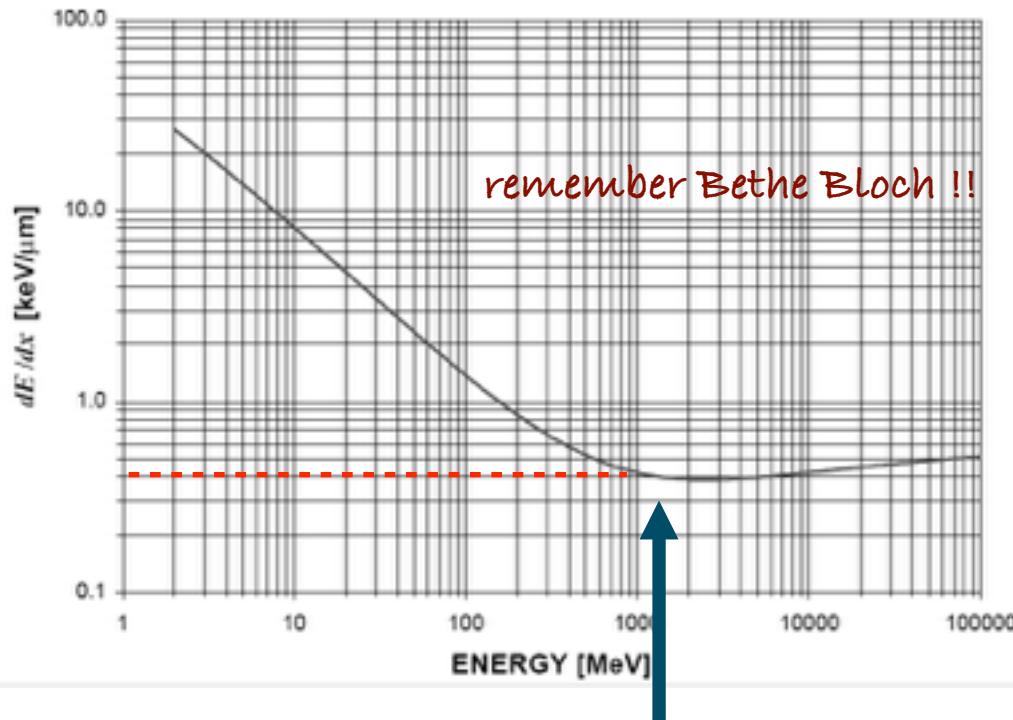
	Si	Ge	GaAs	CdTe	Diamond	SiC
band gap	1.12	0.67	1.42	1.56	5.48	2.99
energy for e-p pair [eV]	3.6	2.9	4.2	4.7	13.1	6.9
e- for MIP (300μm)	24000	50000	35000	35000	9300	19000
Z	14	32	31+33	48+52	6	14+6

Why is silicon used more often ?

- Silicon is the only material which can be produced in larger areas in high quality
- compare to $kT = 0.026 \text{ eV}$ at room temperature -> dark current under control
- high density compared to gases: $\rho=2.33\text{g/cm}^3$
- good mechanical stability -> possible to produce mechanically stable layers
- large charge carrier mobility
- fast charge collection $\delta t \sim 10\text{ns}$
- well understood -> radiation tolerant

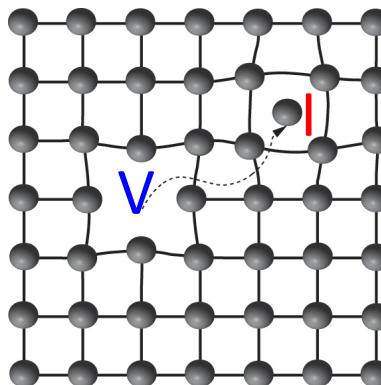


PROTONS IN SILICON



PROBLEM: RADIATION DAMAGE

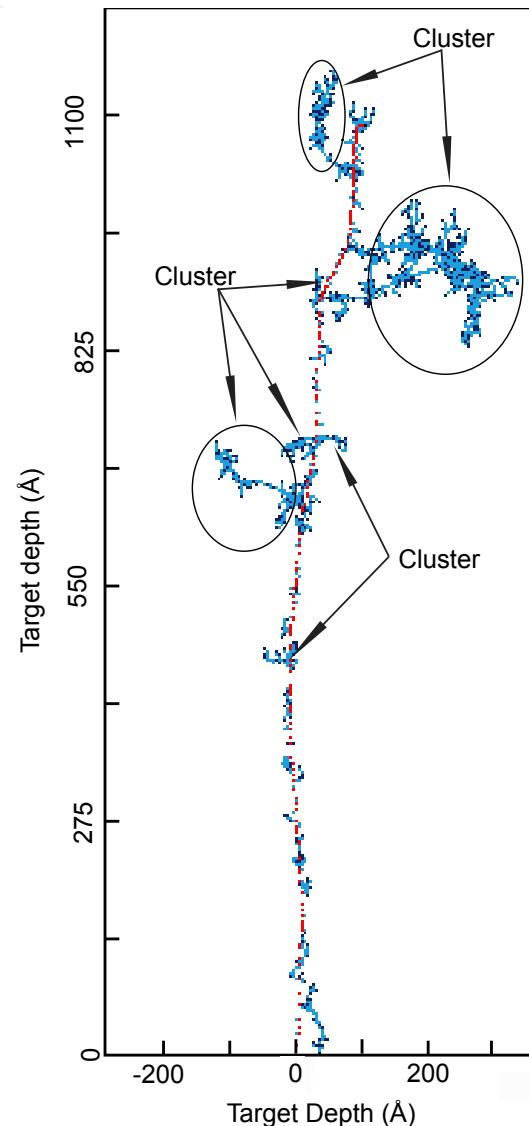
- Radiation damage the silicon on atomic level significantly leading to macroscopic effect.
- Bulk effects:** displacement damage and built up of crystal defects due to Non Ionising Energy Loss (NIEL) (**main problem for sensors**).
unit: 1MeV equivalent n/cm² (up to 10^{15} n_{eq}/cm²)



Defects composed of:
Vacancies and Interstitials

Compound defects with
impurities possible!

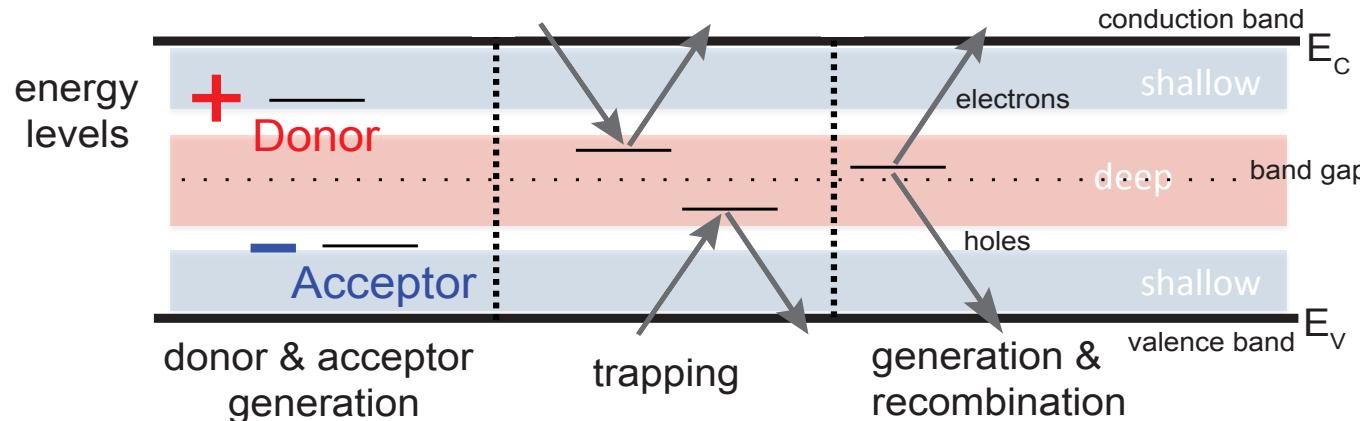
- Surface effects:** Generation of charge traps due to ionizing energy loss (Total ionising dose, TID)
(main problem for electronics).
unit: Rad (up to 100 MRad)



Simulation of 50 keV PKA damage cascade (1 MeV n)

RADIATION DAMAGE: BULK DEFECTS

- Impact of defects on detector properties depends on defect level in band gap



Change of effective doping concentration (N_{eff})

Can contribute to space charge:

- increase of depletion voltage
- under-depleted operation

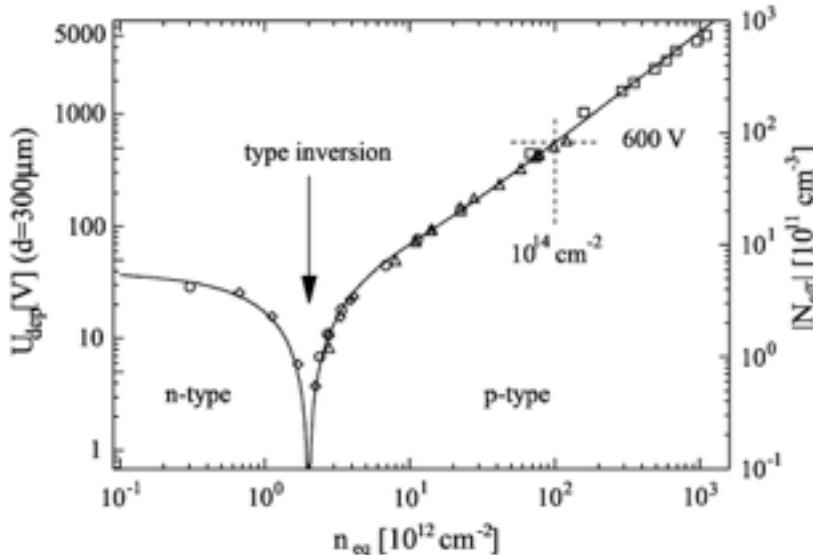
Increased charge trapping

Loss of signal (reduced charge collection efficiency)

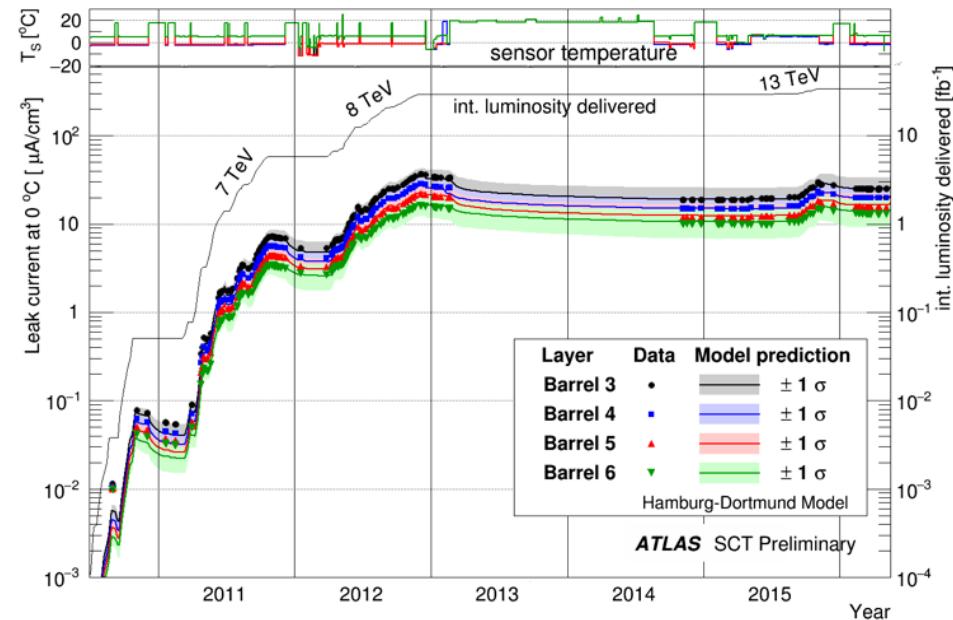
Increase of leakage current
higher shot noise
thermal runaway

CONSEQUENCES OF RADIATION DAMAGE

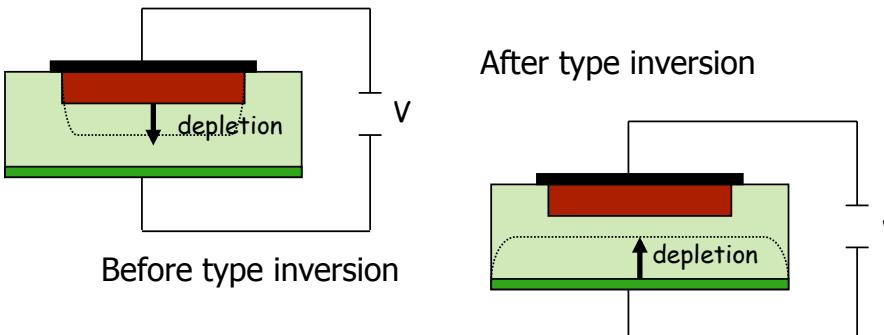
Change of depletion voltage V_{dep} (N_{eff})



Change of leakage current (after hadron irradiation)



Type inversion: N_{eff} changes from positive to negative



Counter measures

- Geometrical: develop sensors that can withstand higher depletion voltages
- Thinner sensors (but FE electronics with higher sensitivity needed)
- Environment: sensor cooling ($-10 - 20^\circ\text{C}$)
- Oxygen-rich Si can help: depletion voltage

COFFEE BREAK ??

